SMT inductors

SIMID series, SIMID 1812-T

Series/Type: **B82432T**

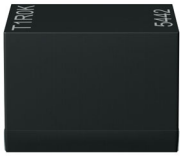
Date: June 2026

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Size 1812 (EIA) or 4532 (IEC)
Rated inductance 1 ... 1000 µH
Rated current 70 ... 1300 mA



Construction

- Upright ferrite drum core
- Laser-welded winding
- Flame-retardant molding

Features

- Temperature range up to +150 °C
- High current handling capability
- Qualified to AEC-Q200
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD-020
- RoHS-compatible

Applications

- Filtering of supply voltages, coupling, decoupling
- DC/DC converters
- Automotive electronics (e.g. single-wire bus systems)
- Telecommunications
- Industrial electronics

Terminals

- Base material CuSn6
- Layer composition Cu, Ag, Sn (lead-free)[1)]
- Electro-plated

Marking

- Marking on component:
  Letter “T”,
  L value (in µH), tolerance of L value (coded),
  date of manufacture (YWWD)
- Minimum data on reel:
  Manufacturer, ordering code, L value, quantity, date of packing

Delivery mode and packing unit

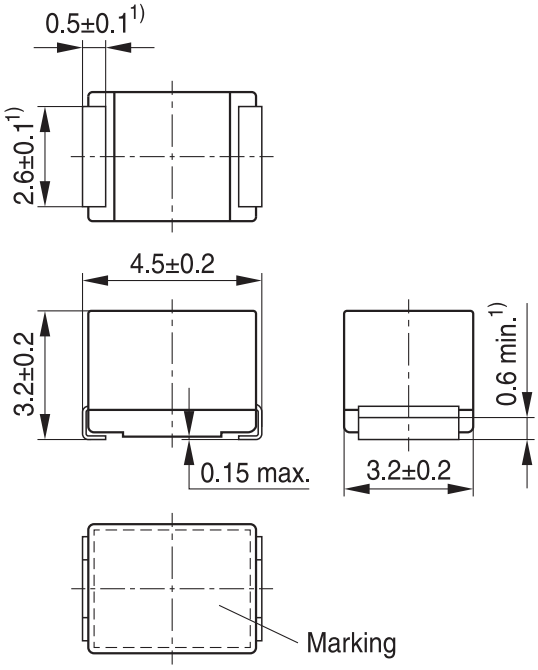
- 12-mm blister tape, wound on 330-mm ∅ reel
- Packing unit: 2500 pcs./reel

1) Ni-barrier-plated terminals on request (B82432T*50).

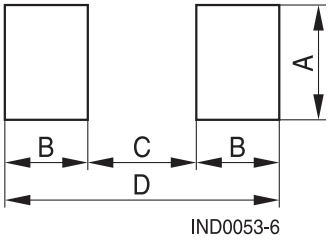
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Dimensional drawing and layout recommendation



1) Soldering area IND0083-T-E



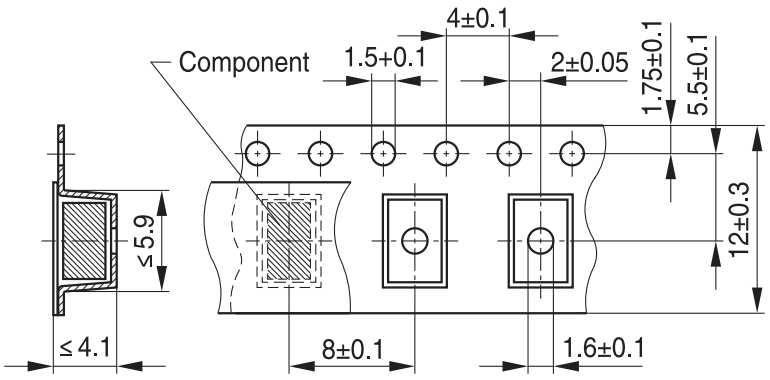
IND0053-6

A	B	C	D
3.6	1.3	3.2	5.8

Dimensions in mm

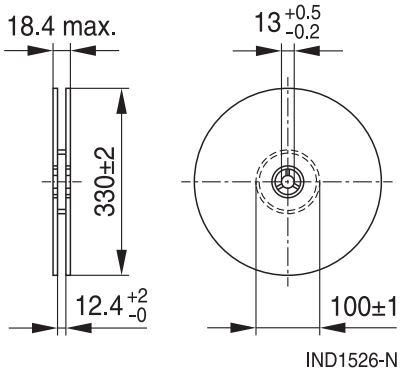
Taping and packing

Blister tape



IND0561-L-E

Reel



IND1526-N

Dimensions in mm

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Technical data and measuring conditions

Rated inductance L_R	Measured with impedance analyzer Agilent 4294A or equivalent at frequency f_L, 0.1 V, +20 °C
Q factor Q_{min}	Measured with impedance analyzer Agilent 4294A or equivalent at frequency f_Q, +20 °C
Rated temperature T_R	+85 °C
Rated current I_R	Maximum permissible DC with inductance decrease $\Delta L/L_0 \leq 10\%$ and temperature increase of ≤ 40 K at rated temperature
Self-resonance frequency $f_{res,min}$	Measured with impedance analyzer Agilent 4294A / E4991A or equivalent, +20 °C
DC resistance R_{max}	Measured at +20 °C
Solderability (lead-free)	Sn95.5Ag3.8Cu0.7: +(245 ±5) °C, (5 ±0.3) s Wetting of soldering area ≥ 90% (based on IEC 60068-2-58)
Resistance to soldering heat	+260 °C, 40 s (as referenced in JEDEC J-STD-020)
Climatic category	55/150/56 (to IEC 60068-1)
Storage conditions	Mounted: –55 °C … +150 °C Packaged: –25 °C … +40 °C, ≤ 75% RH
Weight	Approx. 130 mg

Characteristics and ordering codes

L_R µH	Tolerance	Q_{min}	f_L; f_Q MHz	I_R mA	R_{max} Ω	$f_{res,min}$ MHz	Ordering code[1)]
1.0	±10% ≙ K	10	7.96	1300	0.08	110	B82432T1102K000
1.2		10	7.96	1200	0.10	100	B82432T1122K000
1.5		10	7.96	1150	0.11	80	B82432T1152K000
1.8		10	7.96	1050	0.13	70	B82432T1182K000
2.2		10	7.96	1000	0.15	60	B82432T1222K000
2.7		10	7.96	950	0.17	55	B82432T1272K000
3.3		10	7.96	900	0.19	50	B82432T1332K000
3.9		10	7.96	850	0.20	45	B82432T1392K000
4.7		10	7.96	800	0.22	40	B82432T1472K000
5.6		10	7.96	750	0.26	38	B82432T1562K000
6.8		10	7.96	700	0.30	36	B82432T1682K000
8.2		10	7.96	670	0.33	30	B82432T1822K000

1) For Ni-barrier-plated terminals replace the last two digits “00” by “50”.

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Characteristics and ordering codes

L_R µH	Tolerance	Q_{min}	f_L; f_Q MHz	I_R mA	R_{max} Ω	$f_{res,min}$ MHz	Ordering code[1)]
10	± 10 % ≙ K	10	2.52	650	0.35	25	B82432T1103K000
12		10	2.52	630	0.45	23	B82432T1123K000
15		10	2.52	600	0.50	20	B82432T1153K000
18		10	2.52	550	0.60	18	B82432T1183K000
22		10	2.52	450	0.70	15	B82432T1223K000
27		10	2.52	430	1.00	14	B82432T1273K000
33		10	2.52	400	1.20	13	B82432T1333K000
39		10	2.52	380	1.30	12	B82432T1393K000
47		10	2.52	350	1.35	11	B82432T1473K000
56		10	2.52	300	2.00	10	B82432T1563K000
68		10	2.52	250	2.50	8.0	B82432T1683K000
82		10	2.52	220	3.00	7.0	B82432T1823K000
100		20	0.796	200	3.50	6.5	B82432T1104K000
120		20	0.796	180	4.50	6.3	B82432T1124K000
150		20	0.796	160	6.00	6.1	B82432T1154K000
180		20	0.796	140	7.00	5.5	B82432T1184K000
220		20	0.796	130	7.50	4.5	B82432T1224K000
270		20	0.796	120	10.5	4.3	B82432T1274K000
330		20	0.796	120	11.0	4.1	B82432T1334K000
390		20	0.796	110	13.0	3.9	B82432T1394K000
470		20	0.796	100	15.0	3.5	B82432T1474K000
560		20	0.796	90	20.0	3.0	B82432T1564K000
680		20	0.796	80	23.0	2.6	B82432T1684K000
820		20	0.796	80	27.0	2.4	B82432T1824K000
1000		20	0.252	70	30.0	2.3	B82432T1105K000

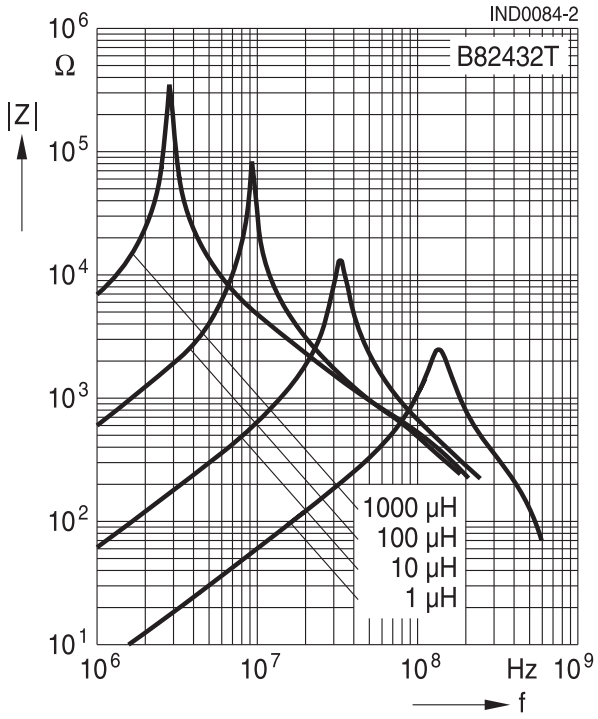
Closer tolerances on request.
Higher currents possible at temperatures $<T_R$ on request.

1) For Ni-barrier-plated terminals replace the last two digits of ordering code “00” by “50”.

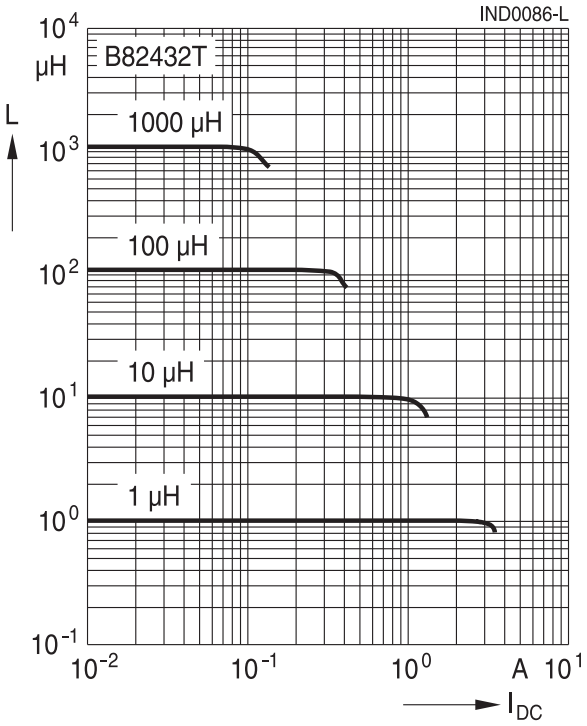
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Impedance |Z| versus frequency f
measured with impedance analyzer Agilent E4991A, typical values at +20 °C

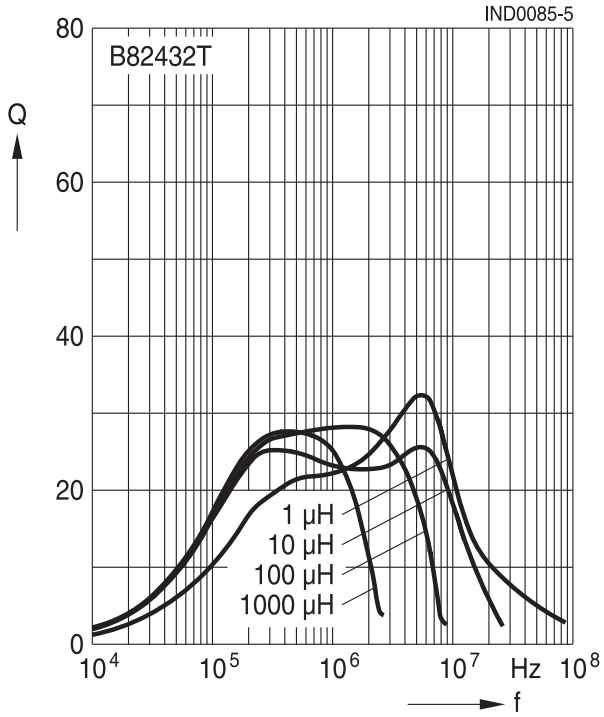


Inductance L versus DC load current I_{DC}
measured with LCR meter Agilent 4285A, typical values at +20 °C



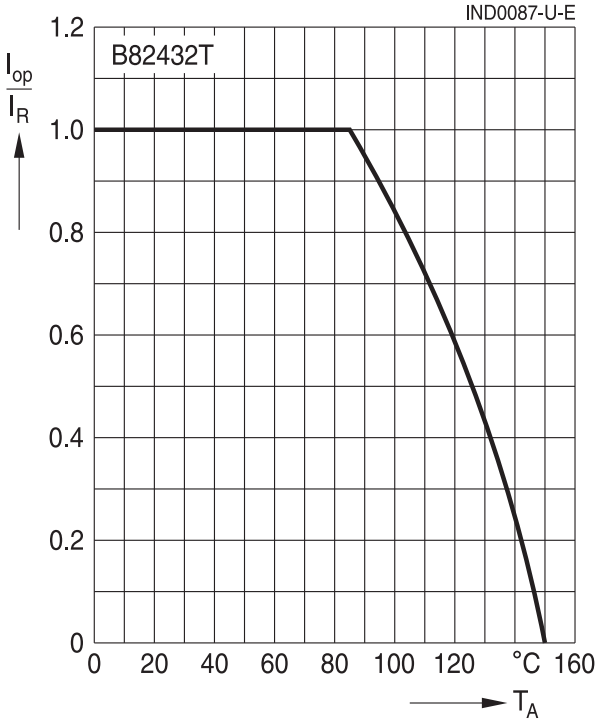
Q factor versus frequency f

measured with impedance analyzer Agilent 4294A, typical values at +20 °C



Current derating I_{op}/I_R versus ambient temperature T_A

(rated temperature T_R = +85 °C)



Please read *Cautions and warnings* and *Important notes* at the end of this document.

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Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition), online catalogs and in the data sheets.
  - Particular attention should be paid to the derating curves, if given. Derating applies in the case the ambient temperature in application exceeds the rated temperature of the component.
  - Ensure the operation temperature of the component in application not to exceed the maximum specified value or the upper climatic category temperature.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pins only. Temperatures specified in relation to reflow soldering can also refer to the pins or terminals for products with larger thermal mass, as in such cases, the temperature difference to the top of the component is too big (e.g., high proportion of core within the component).

- If the components are to be washed or varnished it is necessary to check whether the washing or varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. It is possible for washing or varnish agent residues to have a negative effect in the long-term on wire insulation.
  Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.

- The following points must be observed if the components are potted, sealed, or varnished in customer applications:
  - Many potting, sealing, or varnishing materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting, sealing, or varnishing materials used attack or destroy the wire, wire insulation, plastics or glue.
  - The effect of the potting, sealing, or varnishing materials may change the high-frequency behavior of the components.
  - Many coating materials have a negative effect (chemically and mechanically) on the winding wires, insulation materials and connecting points. Customers are always obliged to determine whether and to what extent their coating materials influence the component. Customers are responsible and bear all risk for the use of the coating material. TDK Electronics does not assume any liability for failures of our components that are caused by the coating material.

- Magnetic core materials such as ferrites are sensitive to direct impact. This can cause the core material to flake or lead to breakage of the magnetic core material.

- Any type of tension or pressure on the product may result in damage and affect its functionality and reliability.
  - The products are only to be attached to fixings or mounting holes provided for this purpose in accordance with the data sheet.
  - If additional mechanical forces are applied to the component, e.g., application of gap pads, it is necessary to check whether they attack or destroy any part of the component.
  - It is not permitted for the product specified in the data sheet to assume a mechanical function in the final application.
- Inductance value can drop if external metallic or magnetic parts will be put close to the coil or into the air gap of the coil or core or magnetic material.

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- Due to product design and applied manufacturing process, appearance, symmetry, and shape of not dimensioned details could vary within same lot, as well discoloration of housing is possible.TDK does not expect detrimental effects on product function or reliability. In case of conflicts,TDK reference standard shall prevail.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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The ordering code for one and the same product can be represented differently in data sheets, data books, other publications, on the company website, or in order-related documents such as shipping notes, order confirmations and product labels. **The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products.** Detailed information can be found on the Internet under www.tdk-electronics.tdk.com/orderingcodes.

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1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.

2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.

3. **The warnings, cautions and product-specific notes must be observed**.

4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (www.tdk-electronics.tdk.com/material). Should you have any more detailed questions, please contact our sales offices.

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   We also **reserve the right to discontinue production and delivery of products**. Consequently, we cannot guarantee that all products named in this publication will always be available. The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.

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Important notes

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